

CLAIMS

1. A hot-melt adhesive composition containing as a main component a crystalline compound having a melting temperature of 50 to 300°C, said composition having a 5 melting temperature width of not more than 30°C and having a melt viscosity of not more than 0.1 Pa·s at a melting temperature of the composition.
2. The hot-melt adhesive composition as claimed in 10 claim 1, wherein the crystalline compound is an organic compound composed of elements of C, H and O only and having a molecular weight of not more than 1000.
3. The hot-melt adhesive composition as claimed in 15 claim 1 or 2, wherein the total of an alkali metal ion content and a heavy metal ion content in the composition is not more than 100 ppm.
4. The hot-melt adhesive composition as claimed in 20 any one of claims 1 to 3, wherein the crystalline compound is an aliphatic compound or an alicyclic compound.

5. The hot-melt adhesive composition as claimed in
any one of claims 1 to 3, wherein the crystalline
compound is a compound having a steroid skeleton and/or a
hydroxyl group in a molecule or a derivative thereof
5 (except an ester derivative).

6. The hot-melt adhesive composition as claimed in
any one of claims 1 to 5, which contains a surface
tension modifier.

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7. The hot-melt adhesive composition as claimed in
claim 6, wherein the surface tension modifier is at least
one substance selected from the group consisting of
fluorine-based surface active agents having a fluorinated
15 alkyl group and polyether alkyl-based surface active
agents having an oxyalkyl group.

8. The hot-melt adhesive composition as claimed in
any one of claims 1 to 7, which has properties that a
20 bond strength A (MPa) at a temperature of 25±2°C that is
given when a wafer and a glass substrate are bonded using
the composition and a bond strength B (MPa) at a
temperature lower than the melting temperature of the
composition by 20°C that is given when they are bonded

using the composition satisfy the following relational expression (1):

$$0 < A - B < 0.5 \quad (1)$$

5 9. The hot-melt adhesive composition as claimed in
any one of claims 1 to 8, which is in the form of a
tablet.

10 10. A hot-melt adhesive kit comprising the tablet
hot-melt adhesive composition of claim 9, a surface
treatment agent and a cleaning liquid.